

Appln No. 10/713,065
Amdt. Dated 3 February 2005
Response to Office action of 27 December 2004

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Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A printhead assembly comprising:
a printhead support beam formed from an odd number of layers, there being a pair of outer layers symmetrically disposed about and laminated to a core, the coefficient of thermal expansion of the core and the outer layers providing a coefficient of expansion, in the beam, substantially equal to that of silicon wherein:
the coefficients of thermal expansion of the outer layers and the core are different.
2. (Previously Presented) The printhead assembly of claim 1, wherein:
the outer layers are the same thickness.
3. (Previously Presented) The printhead assembly of claim 1, wherein:
the outer layers are made from invar.
4. (Cancelled)
5. (Previously Presented) The printhead assembly of claim 1, wherein the beam is elongate, the assembly further comprising:
a plurality of printhead modules positioned end to end along the beam.
6. (Previously Presented) The printhead assembly of claim 5, wherein:
the printhead modules are all silicon MEMS type modules.
7. (Previously Presented) The printhead assembly of claim 1, wherein:
the layers are hot rolled.
8. (Previously Presented) The printhead assembly of claim 7, wherein:
the layers are three in number and the core has a coefficient of thermal expansion greater than that of silicon.